

Product Specification

Model Name	S024HQ42NN		
	TFT LCD Module		
Description	2.4" QVGA		
	240(RGB)x320 Dots		
Date	2020/9/11		
Version	2.0		

Approved	Check	Prepared	
by/Date	by/Date	by/Date	
	ZHP 2020/9/11	Yigui.Han 2018/3/27	

Customer Approval						
Date						



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1. Record of Revision

Rev	Issued Date	Description	Editor
1.0	2019/3/27	First Release.	Yigui.Han
2.0	2020/9/11	Updated the Temp data.	ZHP



2. General Specifications

	Feature	Spec		
	Size	2.4 inch		
	Resolution	240(horizontal)*320(Vertical)		
	Interface	MCU8/16 bit /RGB 18bit/SPI		
	Connect type	Connector		
	Display Colors	262K		
Characteristics	Technology type	a-Si		
	Pixel pitch (mm)	0.153*0.153		
	Pixel Configuration	R.G.BStripe		
	Display Mode	Normally Black		
	Driver IC	ILI9340X		
	Viewing Direction	Full view		
	LCM (W x H x D) (mm)	42.72*60.26*2.20		
Maabariaal	Active Area(mm)	36.72*48.96		
Mechanical	Weight (g)	TBD		
	LED Numbers	4 LEDs		

Note 1: Requirements on Environmental Protection: RoHs

Note 2: LCM weight tolerance: +/- 5%



3. Input/Output Terminals

LCD PIN-MAP

PIN NO.	PIN NAME	DESCRIPTION						
1	VCI	Power supply.						
2	IOVCC	Digital power supply.						
3	IM0	1 0 0 0 80 MCU 16-bit bus D[8:1] D[17:10], D[8:1]						
		1 0 0 1 80 MCU 8-bit bus D[17:10] D[17:10]						
4	IM3	1 0 1 0 80 MCU 18-bit bus D[8:1] D[17:0]						
5	IM2	1 0 1 1 80 MCU 9-bit bus D[17:10] D[17:9]						
		1 1 0 1 3-wire 9-bit data serial SDI: In interface II SDO: Out						
6	IM1	4-wire 8-bit data serial SDI: In						
		1 1 0 interface II SDO: Out						
7	RESET	Reset signal input terminal						
8	VSYNC	Vertical Sync signal						
9	HSYNC	Horizontal Sync signal						
10	DOTCLK	Dot clock signal.						
11	ENABLE	Data Enable						
12~29	DB17~DB0	DATA BUS.						
30	SDO	Serial output data						
31	SDI	Serial Input Data.						
32	RD	Read signal						
33	WR/(D/CX)	8080-I system :Write signal Serial interface: Data or command select.						
34	RS/(SCL)	8081-I system :Data or command select. Serial interface:Serial clock signal.						
35	CS	Chip select						
36	GND	System Ground						
37	LEDA	LED Anode.						
38	LEDK	LED Cathode.						
39	LEDK	LED Cathode.						
40	NC	No connection						
41	NC	No connection						
42	NC	No connection						
43	NC	No connection						
44	NC	No connection						
45	NC	No connection						
	· · · · -							



4. Absolute Maximum Rating

Driving TFT LCD Panel

Item	Symbol	MIN	MAX	Unit	Remark
Supply Voltage	V _{CC}	2.5	4.6	V	
Input Voltage	IOVCC	1.65	4.6	V	
Operating Temperature	T _{OPR}	-20	70	$^{\circ}$	
Storage Temperature	T _{STG}	-30	80	$^{\circ}$	

5. Timing characteristics

5.1 ELECTRICAL CHARACTERISTICS

Item		Symbol	MIN	TYP	MAX	Unit	Remark
Analog Supp	ly Voltage	V _{CC}	2.5	2.8	3.3	V	
Logic Signal Input /Output Voltage		IOVCC	1.65	1.8	3.3	V	
Input Signal	Low Level	VIL	VSS - 0.3x			V	
Voltage	High Level	V _{IH}	0.7x IOVCC	-	IOVCC	V	
TFT Common Electrode		V _{COMH}	2.5	-	5	V	
TFT Gate ON Voltage		V_{GH}	10	-	16	V	
TFT Gate Of	N Voltage	V_{GL}	-10	-	-5	V	

5.2 LED Driving Conditions

Item	Symbol	MIN	TYP	MAX	Unit	Remark
Forward Current	I_{F}	-	20	-	mA	
Forward Voltage	V_{F}	11.2	12	12.8	V	
Backlight Power consumption	W_{BL}	-	0.24	-	W	
LED Lifetime		-	30000	-	Hrs	



Note 1: Each LED: IF =20 mA, VF =3.2+/0.2V.

Note 2: Optical performance should be evaluated at Ta=25 $^{\circ}$ C only.

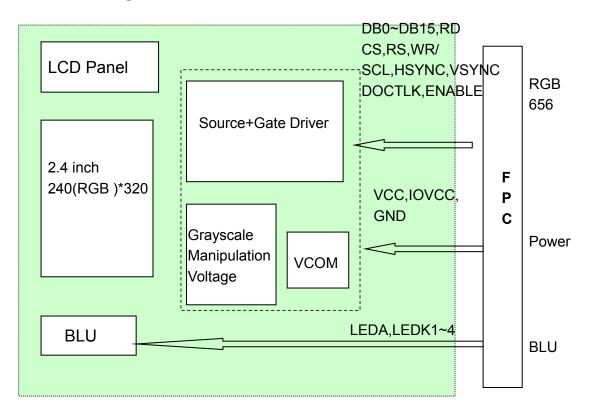
Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life Time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness.

Typical operating life time is estimated data.



Figure: LED connection of backlight(Constant Current)

5.3 Block Diagram





6. Interface Timing

6.1 DC Electrical Characteristics

Item	Symbol	Unit	Condition	Min.	Тур.	Max.	Note
Power and Operation	Voltage				NO 1001	200	X10
Analog Operating Voltage	VCI	٧	Operating voltage	2.5	2.8	3.3	Note2
Logic Operating Voltage	IOVCC	٧	I/O supply voltage	1.65	1.8	3.3	Note2
Digital Operating voltage	VCORE	٧	Digital supply voltage	-	1.5	-	Note2
Gate Driver High Voltage	VGH	٧	-20	10.0	22	15.0	Note3
Gate Driver Low Voltage	VGL	٧	, T-1	-12.6	35	-7.0	Note3
Driver Supply Voltage	25	V	VGH-VGL	19	9	27.6	Note3
Input and Output	0,	387	9.	20.		Šec.	600
Logic High Level Input Voltage	VIH	٧	-	0.7*IOVCC	35	lovcc	Note1,2,3
Logic Low Level Input Voltage	VIL	V	.e.	GND	9	0.3*IOVCC	Note1,2,3
Logic High Level Output Voltage	VOH	٧	IOL=-1.0mA	0.8*IOVCC	g.	IOVCC	Note1,2,3
Logic Low Level Output Voltage	VOL	٧	IOL=1.0mA	GND	2	0.2*IOVCC	Note1,2,3
Logic Input Leakage Current	ILEA	uA	VIN=IOVCC or GND	-0.1	12	+0.1	Note1,2,3
VCOM Operation			· x		-10		
VCOM Amplitude	VCOMA	V			GND		Note3
Source Driver		-07	25	2		800	20:
Source Output Range	Vsout	٧	; = :	VREG2OUT	8	VREGIOUT	Note4

Note 1: IOVCC=1.65 to 3.3V, VCI=2.5 to 3.3V, AGND=GND=0V, Ta=-30 to 80 °C.

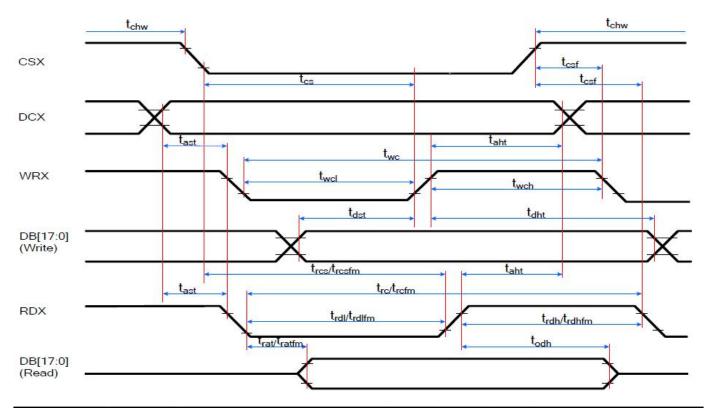
Note2: Please supply digital IOVCC voltage equal or less than analog VCI voltage.

Note3: CSX, RDX, WRX, DB[17:0], DCX, RESX, TE, DOTCLK, VSYNC, HSYNC, ENABLE, SDA, SCL, IM3, IM2, IM1, IM0, and Test pins.

Note4: When the measurements are performed with LCD module. Measurement Points are like Note3.



6.2 Timing

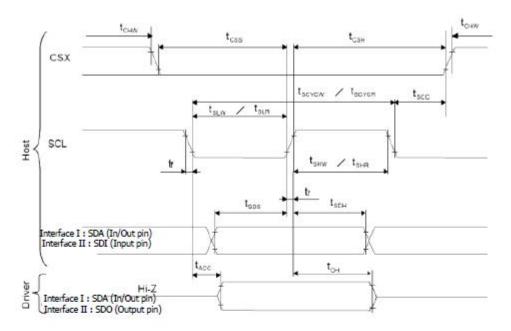


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	N=3	ns	
taht		Address hold time (Write/Read)	10	-	ns	
	tchw	CSX "H" pulse width	0	5 - 8	ns	
	tcs	Chip Select setup time (Write)	15	200	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	250	ns	
	tresfm	Chip Select setup time (Read FM)	355	1 4 0	ns	
	tesf	Chip Select Wait time (Write/Read)	10	949	ns	
	twc	Write cycle	66	120	ns	
WRX	WRX twrh	Write Control pulse H duration	15	120	ns	
		Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	828	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	828	ns	
111	trdlfm	Read Control L duration (FM)	355	329	ns	
	trc	Read cycle (ID)	160	020	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	020	ns	
	trdl	Read Control pulse L duration	45	(2)	ns	
	tdst	Write data setup time	10	N 7 (3)	ns	
DB[17:0],DB[15:0],	tdht	Write data hold time	10	050	ns	Far manimum CI = 20n F
DB[8:0], DB[7:0]	trat	Read access time		40	ns	For maximum CL=30pF For minimum CL=8pF
DB[17:10],DB[8:1]	tratfm	Read access time	-	340	ns	For minimum CL=opF
DB[17:9]	todh	Read output disable time	20	80	ns	

Note: Ta = -30 to 80 °C, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, GND=0V

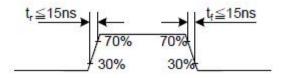
Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080- I /II system)





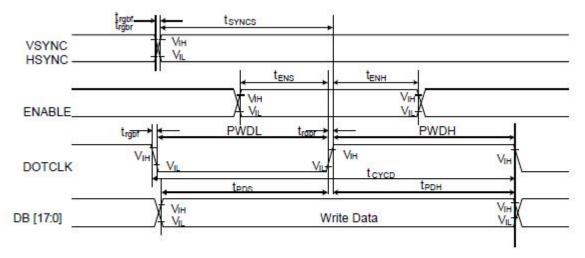
Signal	Symbol	Parameter	min	max	Unit	Description
	t _{scycw}	Serial Clock Cycle (Write)	66	85 .5	ns	3
	t _{shw}	SCL "H" Pulse Width (Write)	33	. 23	ns	
	t _{suw}	SCL "L" Pulse Width (Write)	33	j y	ns	
	tscycw	Serial Clock Cycle (Write RGB data)	15	1 12	ns	MTK-2 lane mode only
SCL	t _{shw}	SCL "H" Pulse Width (Write RGB data)	4	<u> </u>	ns	MTK-2 lane mode only
	tsuw	SCL "L" Pulse Width (Write RGB data)	4	- 6	ns	MTK-2 lane mode only
	tscyce	Serial Clock Cycle (Read)	150		ns	3.
	t _{shR}	SCL "H" Pulse Width (Read)	75	0	ns	
	tsur	SCL "L" Pulse Width (Read)	75	S-35	ns	ts.
SDA / SDI	t _{sps}	Data setup time (Write)	30	85 13	ns	is a second
(Input)	t _{sph}	Data hold time (Write)	30	, 12	ns	15
SDA/SDO	tACC	Access time (Read)	10	J 92	ns	
(Output)	t _{oh}	Output disable time (Read)	10	70	ns	
csx	tscc	SCL-CSX	20	2	ns	
	t _{chw}	CSX "H" Pulse Width	40	- 2	ns	
	tcss		15	12	ns	
	t _{csH}	CSX-SCL Time(write)	15	12	ns	22

Note: Ta = 25 °C, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=GND=0V



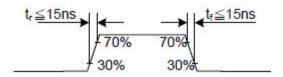
Display Serial Interface Timing Characteristics (3-line SPI system)





Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/	tsyncs	VSYNC/HSYNC setup time	15	100	ns	22
HSYNC	tsynch	VSYNC/HSYNC hold time	15	(C#2)	ns	
ENABLE	tens	ENABLE setup time	15		ns	
ENABLE	tenn	ENABLE hold time	15		ns	
DB[17:0]	teps	Data setup time	15	-	ns	18/16-bit bus RGB
DB[17:0]	t _{PDH}	Data hold time	15	0.40	ns	interface mode
	PWDH	DOTCLK high-level period	33		ns	
DOTCLK	PWDL	DOTCLK low-level period	33		ns	
	toyop	DOTCLK cycle time(18 bit)	66		ns	
	troper, troper	DOTCLK, HSYNC, VSYNC rise/fall time	1 SES	15	ns	
VSYNC/	tsyncs	VSYNC/HSYNC setup time	15	(49)	ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15		ns	
ENABLE	tens	ENABLE setup time	15	(a)	ns]
	tenn	ENABLE hold time	15		ns	
DD147-01	tens	Data setup time	15		ns	6-bit bus RGB
DB[17:0]	t _{PDH}	Data hold time	15	725	ns	interface mode
DOTCLK	PWDH	DOTCLK high-level pulse period	25	1,48	ns	
	PWDL	DOTCLK low-level pulse period	25	-	ns]
DOTOLK	toyop	DOTCLK cycle time (6 bit)	50		ns	
	troper, troper	DOTCLK, HSYNC, VSYNC rise/fall time		15	ns	

Note: Ta = -30 to 80 °C, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=GND=0V

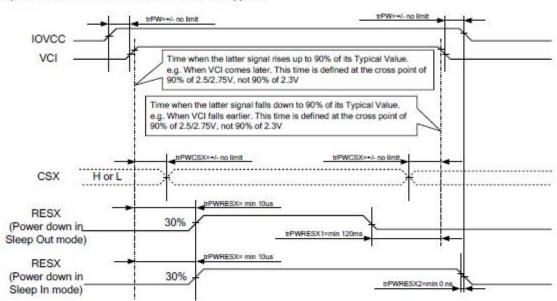


Parallel 18/16/6-bit RGB Interface Timing Characteristics



6.3 Power ON/OFF Sequence

If RESX line is held Low (and stable) by the host during Power On, then the RESX must be held low for minimum 10µsec after both VCI and IOVCC have been applied.



trPWRESX1 is applied to RESX falling in the Sleep Out Mode trPWRESX2 is applied to RESX falling in the Sleep In Mode

Note 1: Unless otherwise specified, timings herein show cross point at 50% of signal power level.



7. Optical Characteristics

Items	,	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	Note	
Response time		Tr+Tf		-	45	65	ms	FIG.1	Note4	
Contrast Ratio		CR	-	300	350	-	-	FIG.2	Note1	
Surface luminance		LV	θ =0 °	-	350	-	cd/m2	FIG.2	Note2	
Luminance uniformity		Yu	θ =0°	80	-	-	%	FIG.2	Note3	
NTSC	NTSC		θ =0°	•	60	-	%	FIG.2	Note5	
			θ_{T}	•	80	-	deg	FIG.3		
Viewing a	nalo	θ Cr>10	θ_{B}	•	80	-	deg	FIG.3	Note6	
viewing a	rigie		θ_{L}	•	80	-	deg	FIG.3	Noteo	
		CIZIO	θ_{R}	•	80	-	deg	FIG.3		
Red		R _X		TBD	TBD	TBD	ı			
	Reu	R _Y	R _Y	TBD	TBD	TBD	-			
	0	G _X	θ =0°	TBD	TBD	TBD	-			
Chromaticity	Green	G_Y	∅=0°	TBD	TBD	TBD	-	FIG.2	Noto E	
	Blue	B _X	Ta=25°	TBD	TBD	TBD	-	CIE1931	Note5	
		B _Y	1a=25	TBD	TBD	TBD	-			
	\	W _X		TBD	TBD	TBD	-			
	White	W _Y		TBD	TBD	TBD	-			

Note1. Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula. For more information see FIG.2.

Contrast ratio=

Luminance measured when LCD on the "White" state

Luminance measured when LCD on the "Black" state

For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5 or BM-7 photo detector or compatible.

Note2. Definition of surface luminance.

Surface luminance is the luminance with all pixels displaying white. For more information see FIG.2.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3,,Pn)

Note3. Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

Minimum surface luminance with all white pixels (P1,P2,P3,.....,Pn)

Maximum surface luminance with all white pixels (P1,P2,P3,.....,Pn)

Note4. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and



"Black"state.Rise time (Tr) is the time between photo detector output intensity changed from 90% to 10%. And fall time (Tf) is the time between photo detector output intensity changed from 10% to 90%. For additional information see FIG1.

Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position P5. For more information see FIG.2.

Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. Angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or DMS series Instruments or compatible.

FIG.1.The definition of response Time

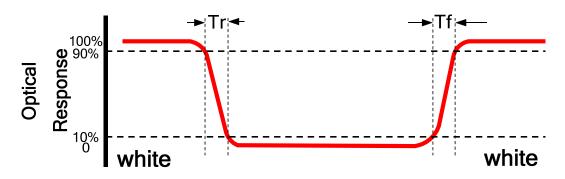


FIG.2. Measuring method for contrast ratio, surface luminance,

luminance uniformity, CIE (x,y) chromaticity

Size : S≤5"(see Figure a) A : 5 mm B : 5 mm

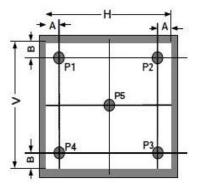
H,V: Active area

Light spot size \oslash =5mm(BM-5) or \oslash =7.7mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens.

test spot position : see Figure a.

measurement instrument: TOPCON's luminance meter BM-5 or

BM-7 or compatible (see Figure c).





Size : 5" < S≤12.3"(see Figure b) H,V : Active area

Light spot size \oslash =5mm(BM-5) or \oslash =7.7mm (BM-7)50cm distance or compatible distance from the LCD surface to detector lens.

test spot position : see Figure b.

measurement instrument: TOPCON's luminance meter BM-5 or

BM-7 or compatible (see Figure c).

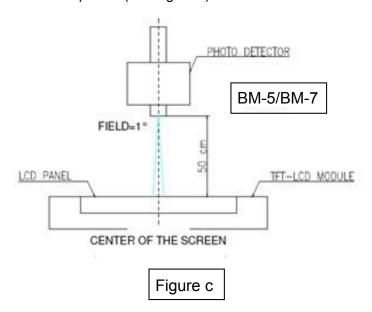


Figure a

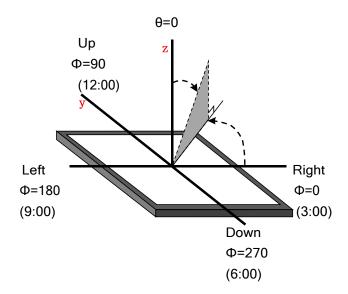
H/6 column

V/6 P1 P2 P3

Row

Figure b

FIG.3. The definition of viewing angle





8. Environmental / Reliability Tests

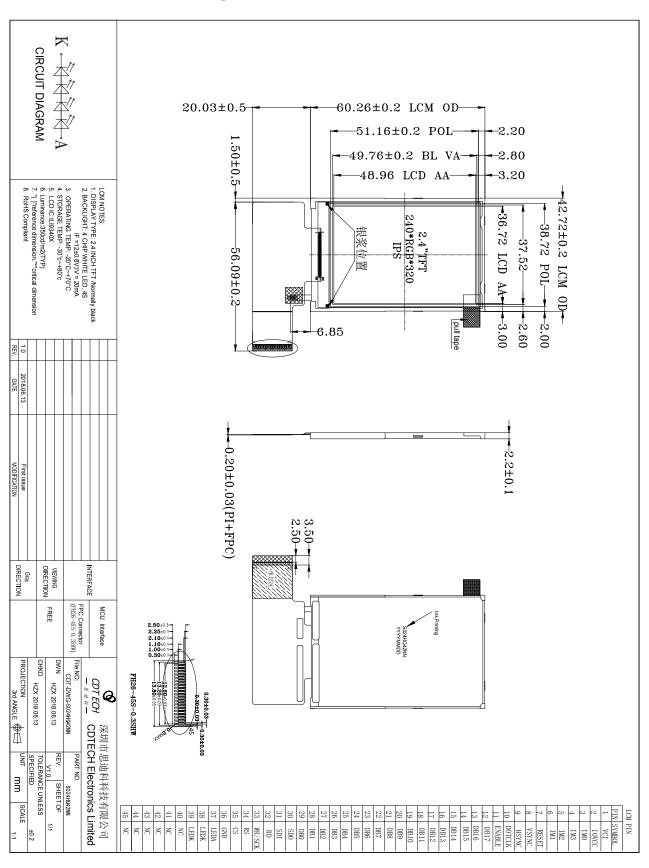
No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts= +70℃, 96hrs	Note 1 IEC60068-2-2, GB2423, 2-89
2	Low Temperature Operation	Ta= -20℃, 96hrs	Note 2 IEC60068-2-1 GB2423.1-89
3	High Temperature Storage	Ta= +80°C, 120hrs	IEC60068-2-2 GB2423. 2-89
4	Low Temperature Storage	Ta= -30℃, 120hrs	IEC60068-2-1 GB/T2423.1-89
5	High Temperature & Humidity Storage	Ta= +60℃, 90% RH max,120 hours	IEC60068-2-3 GB/T2423.3-2006
6	Thermal Shock (Non-operation)	-20℃ 30 min ~ +60℃ 30 min Change time: 5min, 30 Cycle	Start with cold temperature, end with high temperature IEC60068-2-14, GB2423.22-87
7	Electro Static Discharge (Operation)	C=150pF, R=330 Ω, 5 points/panel Air:±8KV, 5 times; Contact: ±4KV, 5 times; (Environment: 15°C ~ 35°C, 30% ~ 60%, 86Kpa ~ 106Kpa)	IEC61000-4-2 GB/T17626.2-1998
8	Vibration (Non-operation)	Frequency range: 10~55Hz, Stroke: 1.mm Sweep: 10Hz~55Hz~10Hz 2 hours for each direction of X .Y. Z. (package condition)	IEC60068-2-6 GB/T2423.5-1995
9	Shock (Non-operation)	60G 6ms, ± X, ±Y, ± Z 3 times for each direction	IEC60068-2-27 GB/T2423.5-1995
10	Package Drop Test	Height: 80 cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8-1995

Note:1. Ts is the temperature of panel's surface.

- 2. Ta is the ambient temperature of sample.
- 3. The size of sample is 5pcs.



9. Mechanical Drawing





10. Packing

Packing Method TBD



11. TFT-LCD Module Inspection Criteria

11.1 Scope

The incoming inspection standards shall be applied to TFT - LCD Modules (hereinafter Called "Modules") that supplied by CDTech Technology LTD.

11.2 Incoming Inspection

The customer shall inspect the modules within twenty calendar days of the delivery date (the "inspection period) at its own cost. The result of the inspection (acceptance or rejection) shall be recorded in writing, and a copy of this writing will be promptly sent to The seller, If the results of the inspecting from buyer does not send to the seller within twenty Calendar days of the delivery date. The modules shall be regards as acceptance. Should the customer fail to notify the seller within the inspection period, the buyers Right to reject the modules shall be lapsed and the modules shall be deemed to have Been accepted by the buyer

11.3 Inspection Sampling

3.1. Lot size: Quantity per shipment lot per model

3.2. Sampling type: Normal inspection, Single sampling

3.3. Inspection level: II

3.4. Sampling table: MIL-STD-105E

3.5. Acceptable quality level (AQL)

Major defect: AQL=0.65 Minor defect: AQL=1.00

11.4 Inspection Conditions

4.1 Ambient conditions:

a. Temperature: Room temperature $25\pm5^{\circ}$ C

b. Humidity: (60 \pm 10) %RH

c. Illumination: Single fluorescent lamp non-directive (300 to 700 Lux)

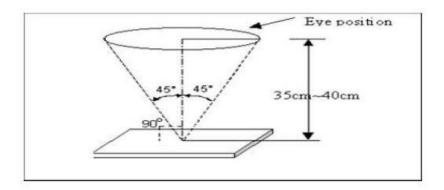
4.2 Viewing distance

The distance between the LCD and the inspector's eyes shall be at least 35 ± 5 cm.

4.3 Viewing Angle

U/D: 45 ° /45° , L/R: 45° /45°





11.5 Inspection Criteria

Defects are classified as major defects and minor defects according to the degree of Defectiveness defined herein.

11.5.1 Major defect

	ion major doloct				
Item No	Items to be inspected	Inspection Standard			
5.1.1	All functional defects	1) No display 2) Display abnormally 3) Short circuit 4) line defect			
`5.1.2	Missing	Missing function component			
5.1.3	Crack	Glass Crack			

11.5.2 Minor defect

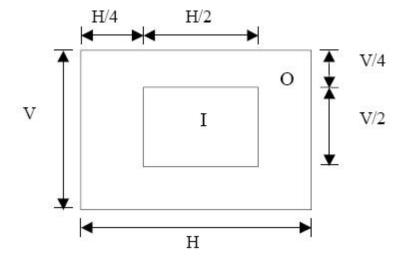
Item No	Items to be inspected	Inspection standard		
5.2.1	Spot Defect Including Black spot White spot Pinhole Foreign	For dark/white spot is defined $\varphi = (x+y) / 2$ $\longrightarrow \begin{array}{c} X \\ \downarrow \\ X \\ \downarrow \end{array}$		
	particle	Size φ(mm)	Acceptable Quantity	
	Polarizer dirt	φ≤0.05	Ignore	
		0.05 < φ ≤ 0.15	2	
		0.15<ф	Not allowed	
5.2.2	Polarizer dirt,	Size Φ(mm)	Acceptable Quantity	



思迪科—	particle	φ≤0.15		1		
		Φ>0.15	Not a	ıllowed		
5.2.3	Line Defect	Define: Vidta Vid	h			
5.2.3	Including Black line White line Scratch	Width(illill) Ecligtii(illill)	Accepta	ble Quantity		
		W≤0.05	Iş	gnore		
		0.05 < W≤0.1 L≤1.5	1			
		0.1 < W, or L>1.5	Not	allowed		
5.2.4	Polarizer Dent/Bubble	Not allowed				
		Bright and Black dot define:				
	Electrical Dot Defect	產點 ■ and				
5.2.5						
		Two Adjacent Dot				
		Inspection pattern: Full white. Fu				
		Item	Accepta I O	ble Quantity Note		
		Black dot defect	1 1 0	Note (5mm≤Distance)		
		Bright dot defect	1	(Jim (Distunct)		
		Two Adjacent Dot	Not allow			



		1.Corner Fragment:		
		Size(mm)	Acceptable Quantity	
		X≤2mm	Ignore	
		Y≤1mm	T: Glass thickness	
		Z≤T	X: Length	
			Y: Width	
5.2.6	Glass defect		Z: thickness	
		2. Side Fragment:		
		Size(mm)	Acceptable Quantity	
		X≤5.0mm	T: Glass thickness	
		Y ≤1mm	X: Length	
		Z≤T	Y: Width	
			Z: thickness	





I area & O area

Note: 1). Dot defect is defined as the defective area of the dot area is larger than 50% of the dot area.

- 2). The distance between two bright dot defects (red, green, blue, and white) should be larger than 15mm.
- 3). The distance between black dot defects or black and bright dot defects should be more than 5mm apart.
- 4). Polarizer bubble is defined as the bubble appears on active display area. The defect of polarizer bubble shall be ignored if the polarizer bubble appears on the outside of active display area.

11.6 Mechanics specification

As for the outside dimension, weight of the modules, please refer to product specification For more details

12. Precautions for Use of LCD modules

12.1 Handling Precautions

- 12.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 12.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 12.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 12.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 12.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents
- 12.1.6. Do not attempt to disassemble the LCD Module.
- 12.1.7. If the logic circuit power is off, do not apply the input signals.
- 12.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an



optimum work environment.

- 12.1.8.1. Be sure to ground the body when handling the LCD Modules.
- 12.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.
- 12.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 12.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

12.2 Storage Precautions

- 12.2.1. When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 12.2.2. The LCD modules should be stored under the storage temperature range If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : 0°C ~ 40°C Relatively humidity: ≤80%

12.2.3. The LCD modules should be stored in the room without acid, alkali and harmful gas.

12.3 Transportation Precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.